

Description

Features

- Trench Power LV MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low RDS(ON)

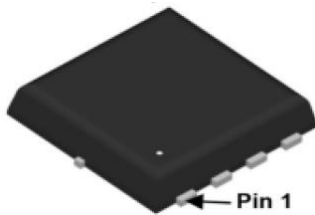
Application

- High current load application
- Load switching
- Quick Charge

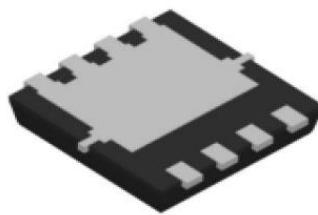
V_{DS}	-30	V
$R_{ds(on),typ}@V_{gs}=-10V$	12	m Ω
$R_{ds(on),typ}@V_{gs}=-4.5V$	19	m Ω
I_D	-30	A



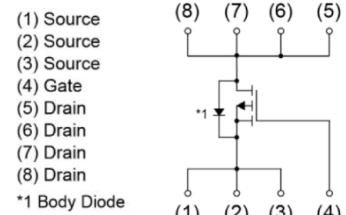
Top View



Bottom View



Pin Configuration



Package Marking and Ordering Information

Part	Marking	Package	Packing	Reel Size	Tape Width	Qty
CMT30P30K	T30P30K	PDFN3.0*3.0	Reel	NA	NA	5000pcs

Key Performance Parameters

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS}=-10V$	-30	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS}=-10V$	-22	A
IDM	Pulsed Drain Current	-110	A
EAS	Single Pulse Avalanche Energy	70	mJ
$PD@T_c=25^\circ C$	Total Power Dissipation	23	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_j	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ	Max	Units
R _{θJA}	Thermal Resistance Junction-Ambient	56	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case	4.9	5.4	°C/W

Electrical Characteristics (T_J=25 °C, Unless otherwise noted)

Symbol	Parameter	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
BVDSS	Drain-Source Breakdown Voltage	-30	--	--	V	V _{GS} =0V, I _D = -250uA
R _{DS(ON)}	Static Drain-Source On-Resistance	--	12	18	mΩ	V _{GS} = -10V, I _D = -10A
		--	19	26		V _{GS} = -4.5V, I _D = -5A
V _{GS(th)}	Gate Threshold Voltage	-1.2	-1.8	-2.5	V	V _{GS} =V _{DS} , I _D = -250uA
IDSS	Drain-Source Leakage Current	--	--	-1	uA	V _{DS} = -30V, V _{GS} =0V, T _J =25°C
		--	--	-30	uA	V _{DS} = -24V, V _{GS} =0V, T _J =125°C
IGSS	Gate-Source Leakage Current	--	--	±100	nA	V _{GS} =±20V, V _{DS} =0V
g _{fs}	Forward Transconductance	--	10.5	--	S	V _{DS} = -10V, I _D = -10A
R _g	Gate Resistance	--	8	--	Ω	V _{DS} =0V, V _{GS} =0V, f=1MHz
Q _g	Total Gate Charge	--	14.6	--	nC	V _{DS} = -15V, V _{GS} = -10V, I _D = -10A
Q _{gs}	Gate-Source Charge	--	4.1	--		
Q _{gd}	Gate-Drain Charge	--	6.3	--		
T _{d(on)}	Turn-On Delay Time	--	9	--	ns	V _{DD} = -15V, V _{GS} = -10V, R _G =3Ω I _D = -10A
T _r	Rise Time	--	21.8	--		
T _{d(off)}	Turn-Off Delay Time	--	59.8	--		
T _f	Fall Time	--	14.4	--		
C _{iss}	Input Capacitance	--	1730	--	pF	V _{DS} = -15V, V _{GS} =0V, f=1MHz
C _{oss}	Output Capacitance	--	180	--		
C _{rss}	Reverse Transfer Capacitance	--	125	--		

Diode Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Units
I _s	Continuous Source Current	V _G =V _D =0V, Force Current	--	--	-30	A
I _{sm}	Pulsed Source Current		--	--	-110	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =-10A, T _J =25°C	--	--	-1.2	V

Note:

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≅ 300us, duty cycle ≅ 2%.
3. Essentially independent of operating temperature.
4. The EAS data shows Max. rating. The test condition is V_{DD}= -20V, V_{GS}= -10V, L=0.5mH.

Typical Performance Characteristics

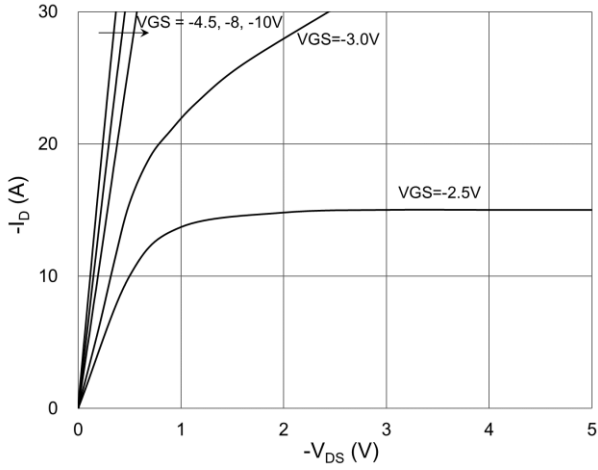
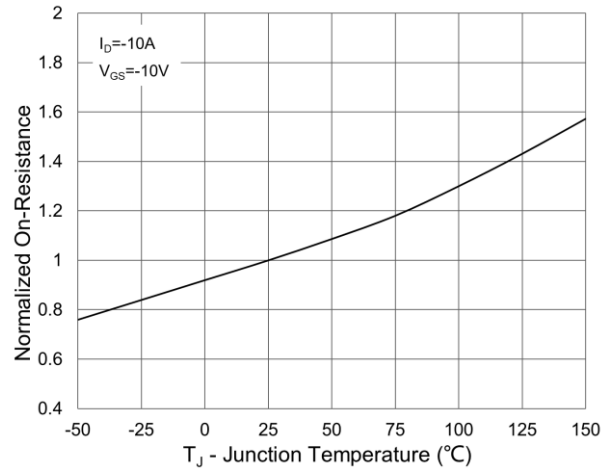
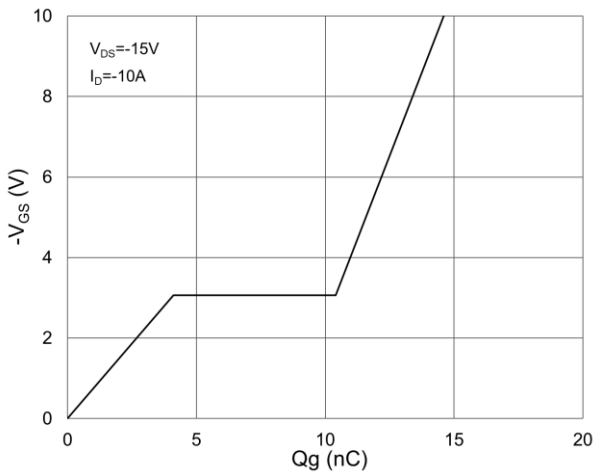
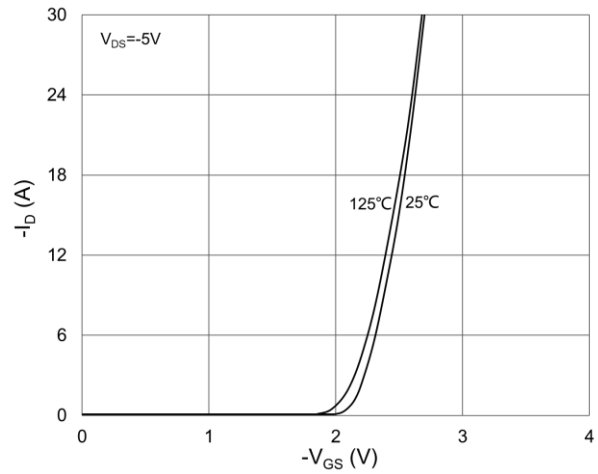
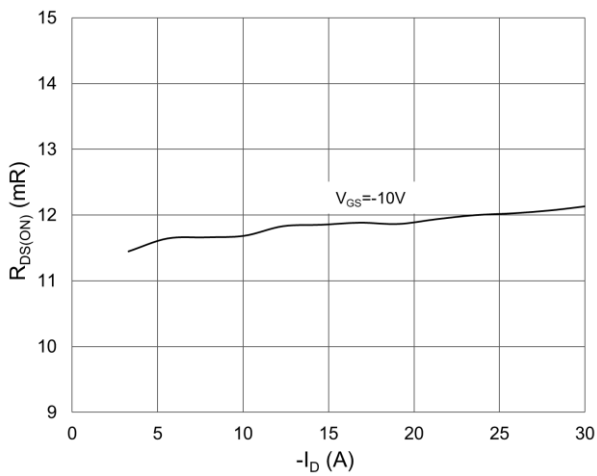
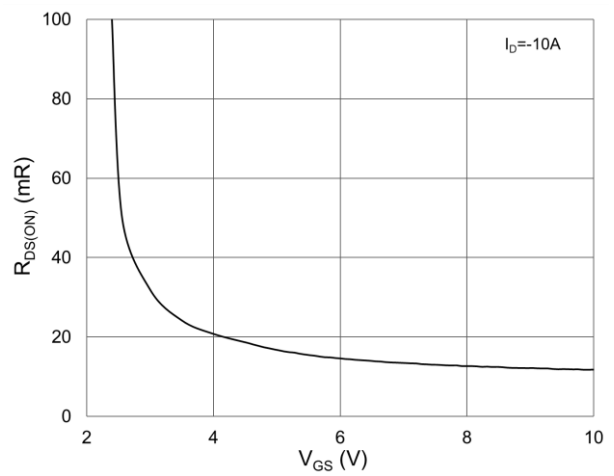
Fig1 Output Characteristics

Fig2 Normalized $R_{DS(on)}$ vs. T_J

Fig3 Gate Charge Waveform

Fig4 Transfer Characteristics

Fig5 $R_{ds(on)}$ vs. Drain Current and Gate Voltage

Fig6 $R_{ds(on)}$ vs. Gate Voltage


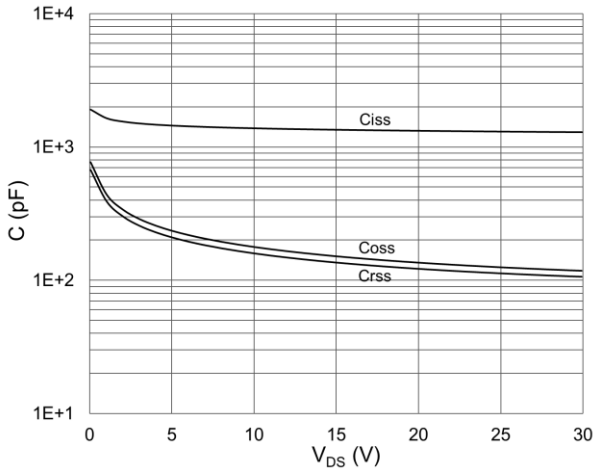
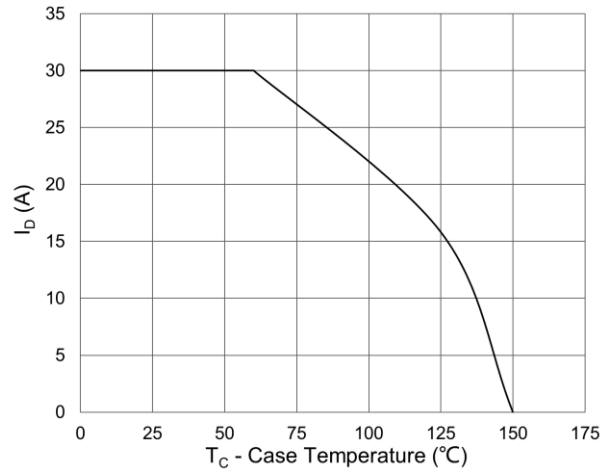
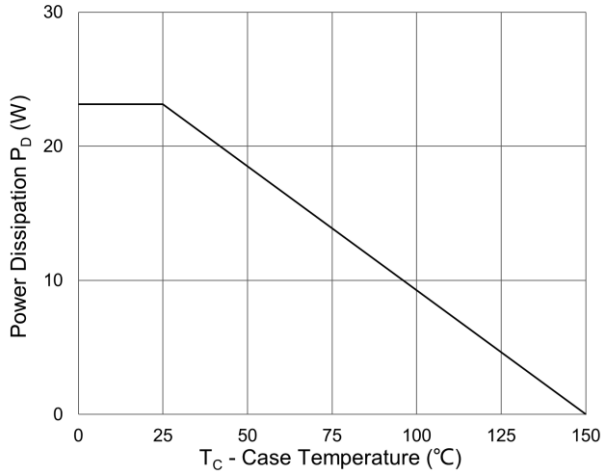
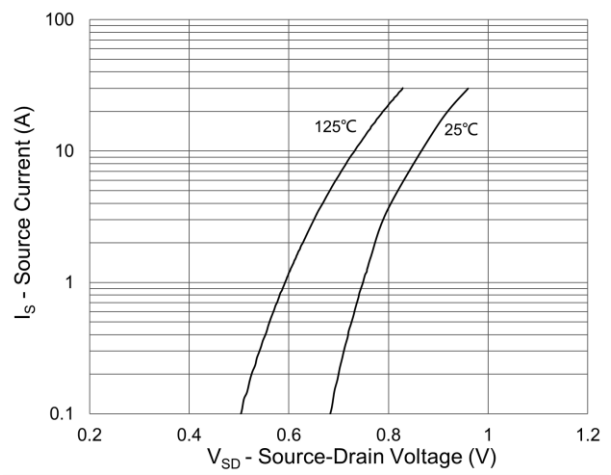
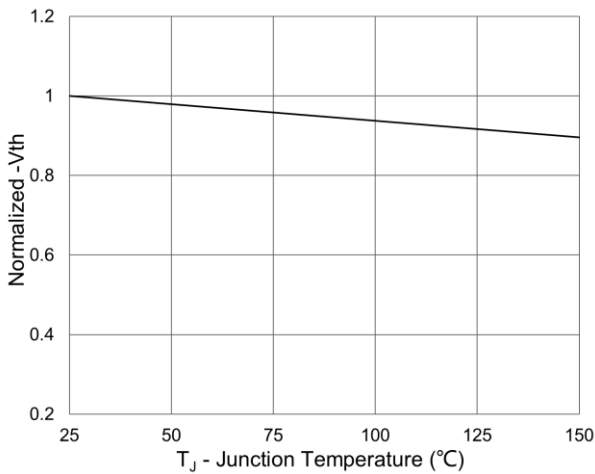
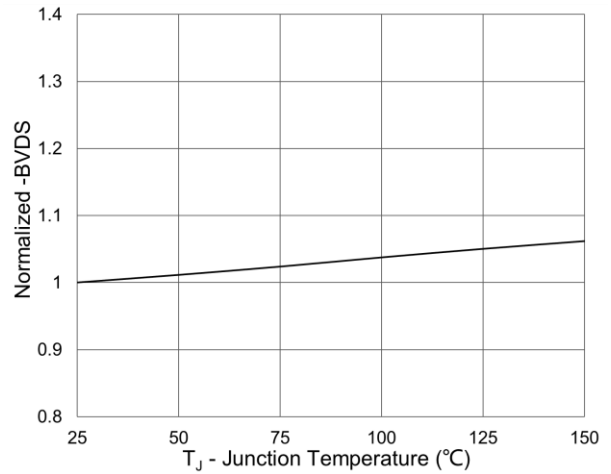
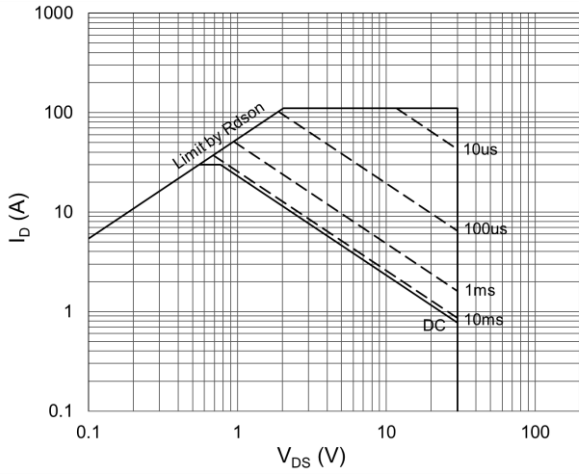
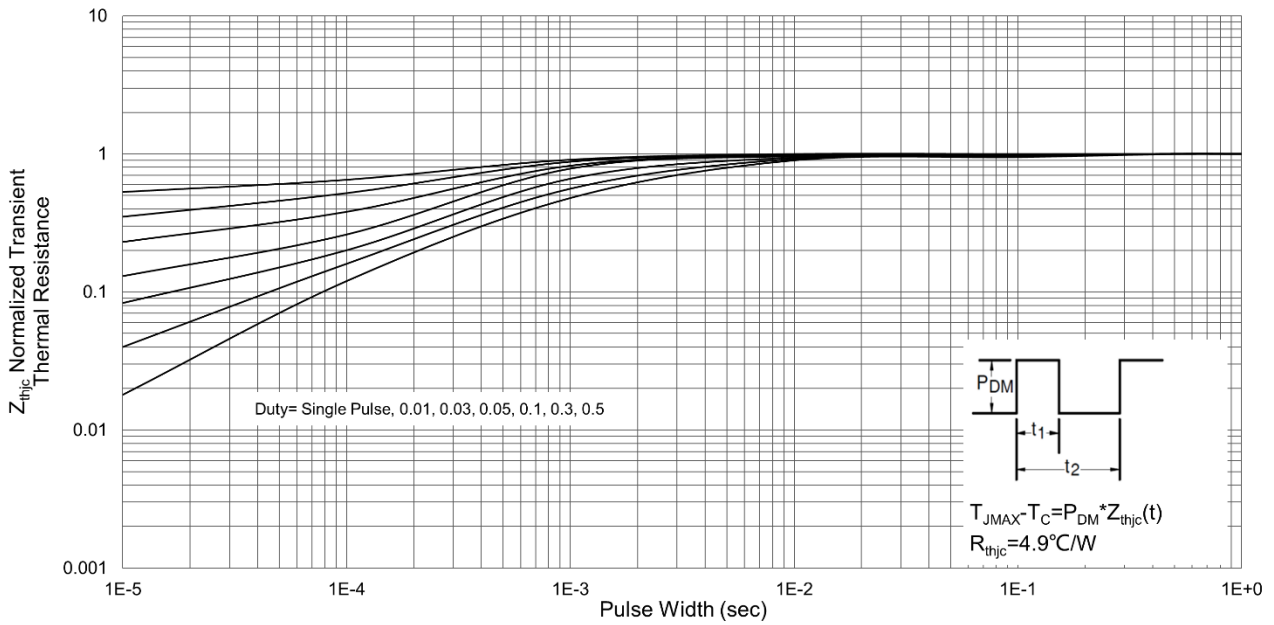
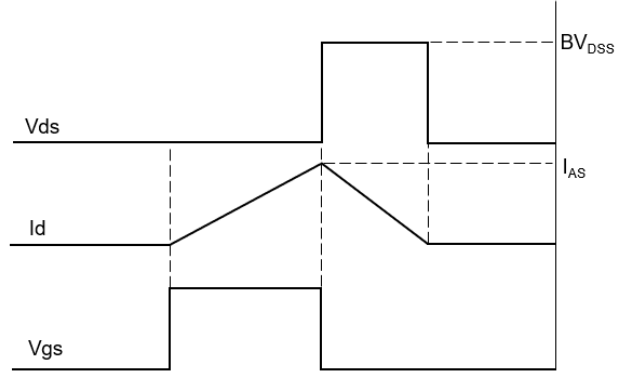
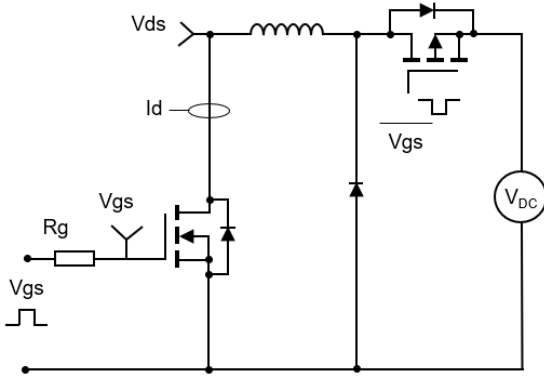
Fig7 Capacitance Characteristics

Fig8 Drain Current Derating

Fig9 Power Dissipation

Fig10 Source-Drain Diode Forward Characteristics

Fig11 Normalized Threshold Voltage vs. T_J

Fig12 Normalized Breakdown Voltage vs. T_J


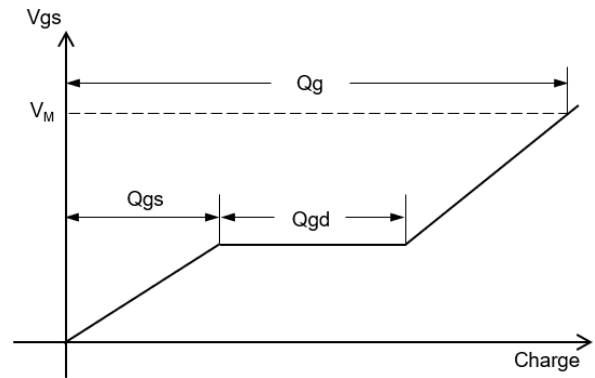
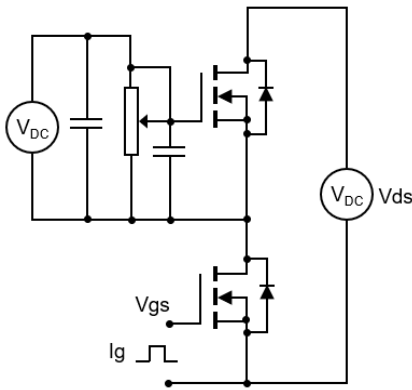
Fig13 Maximum Safe Operation Area

Fig14 Normalized Transient Impedance


Test Circuit & Waveform

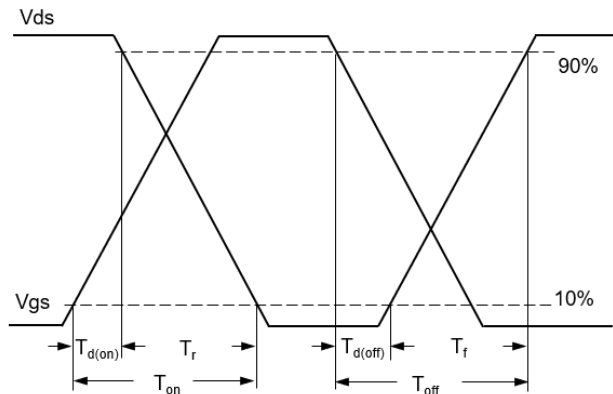
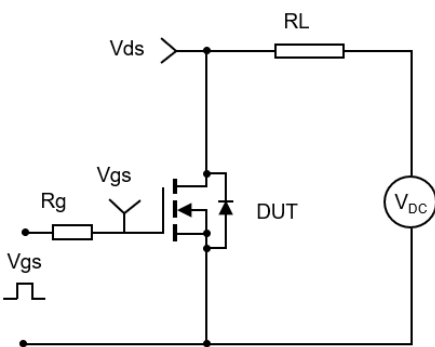
1. Unclamped Inductive Switching Test Circuit & Waveform

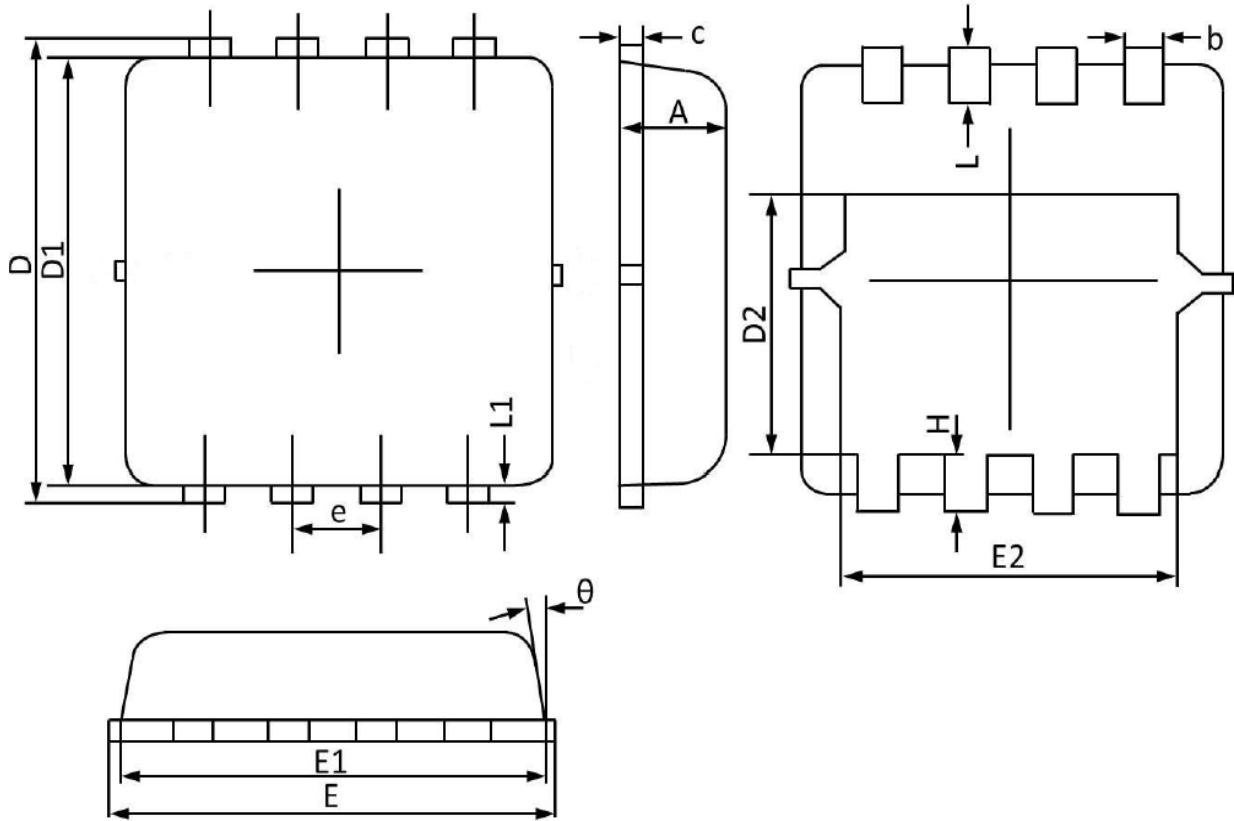


2. Gate Charge Test Circuit & Waveform



3. Resistive Switching Test Circuit & Waveform



PDFN3*3 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.240	0.014	0.009
c	0.250	0.100	0.010	0.004
D	3.450	3.050	0.136	0.120
D1	3.200	2.900	0.126	0.114
D2	1.850	1.350	0.073	0.053
E	3.400	3.000	0.134	0.118
E1	3.250	2.900	0.128	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.500	0.300	0.020	0.012
L	0.500	0.300	0.020	0.012
L1	0.200	0.070	0.008	0.003
θ	12°	0°	12°	0°